

CURABLE COMPOSITIONS

ABSTRACT OF THE DISCLOSURE

A conductive curable resin composition including (a) at least one vinylarene oxide, (b) at least one curing agent, and (c) at least one conductive filler; a process for making the above curable resin composition; and a cured resin composition made
5 therefrom. The curable resin composition when cured produces a thermoset having a higher heat resistance after cure than analogous prior art compositions. The curable compositions of the present invention are advantageously useful, for example, as a die attach adhesive for semiconductor packaging material thermoset materials.

No Figure